

AMENDMENT TO THE CLAIMS:

1-5. (Canceled)

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6. (Original) A method for manufacturing a deposition mask, wherein said deposition mask for placing between a depositing material and a medium on which deposition is performed comprises a semiconductor substrate including an opening forming region having a reduced thickness provided with at least one opening for allowing said depositing material to be selectively attached to a desired position on said medium, and a thick portion formed in at least one portion of a mask outer periphery region of said semiconductor substrate,

said method comprising the steps of:

forming a first coating covering a region in which said thick portion of said semiconductor substrate is to be formed;

using said first coating as an etching mask to etch said semiconductor substrate so as to reduce thickness of said semiconductor substrate and thereby form said opening forming region;

forming a second coating in areas other than a predetermined position within said opening forming region; and

using said second coating as an etching mask to etch said semiconductor substrate so as to form said at least one opening in said predetermined position.

7. (Currently Amended) A method for manufacturing a deposition mask as defined in Claim 6, wherein said semiconductor substrate is composed of silicon.

8. (Currently Amended) A method for manufacturing a deposition mask ~~manufacturing method~~ as defined in Claim 6, wherein

said first coating is formed on a first side of said semiconductor substrate;

said opening forming region is formed by etching said first side of said semiconductor substrate to reduce thickness of said substrate;

said second coating is formed on a second side of said semiconductor substrate; and

said at least one opening is formed by etching from said second side until penetrating through said semiconductor substrate.

9-13. (Canceled)

14. (New) A deposition mask to be placed between a material source and a medium which is a deposition target, comprising:

a plurality of opening forming regions having a plurality of openings for allowing a depositing material to be selectively attached to a desired position on said medium; and

a thick portion formed in an area between said plurality of opening forming regions and on an outer periphery region of said mask, wherein

each of said plurality of opening forming regions has a thickness which is less than that of said thick portion.

15. (New) A deposition mask as defined in Claim 14, wherein
said plurality of opening forming regions correspond to a plurality of display panel regions to be formed on said medium.

16. (New) A deposition mask as defined in Claim 14, wherein
said area between said plurality of opening forming regions in which said thick portion is formed corresponds to a gap position between pixels of a display panel to be formed on said medium.